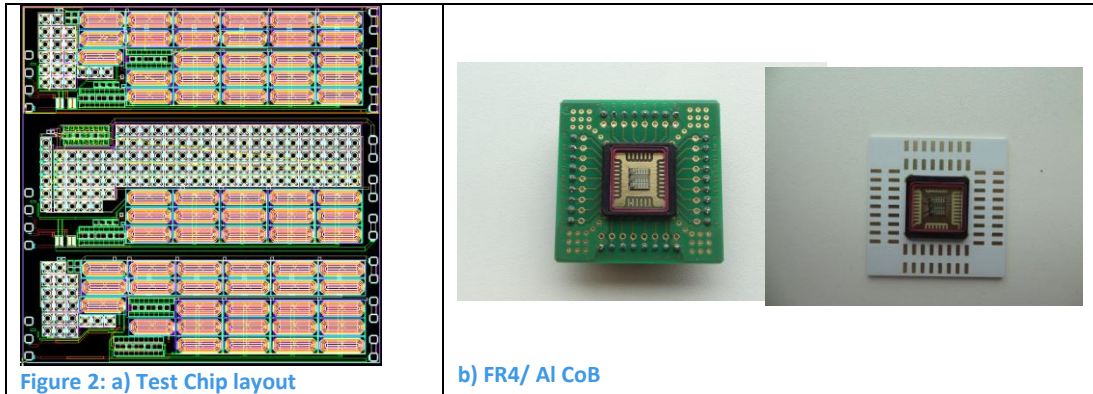


The evaluation has been carried out using CoB (Chip on Board) assemblies of two different carrier materials (FR4/ Aluminum Figure 2 b).



Based on the results of the test chip a final HV ASIC could be developed and fabricated. The methodology of this HV ASIC design follows the ideas of:

- Accessibility to each relevant subcircuit in order to enable a single characterization
- Decoupling of subsystem functionalities by turn_off features in order to ensure full system functionality even in case of single malfunctions which may be fixed by external circuitries.
- Each HV stage can be powered separately and can drive a maximum load of 100 nF parallel to 50 kΩ.
- Energy saving/ Power management by phase shift unit
- HV operation emergency stop in case of excessive heating by integrated temperature control with automatic turn_off
- Simulations were done with respect to save start-up, technology tolerances, temperature range and functionalities (e.g. Figure 3, Figure 4).

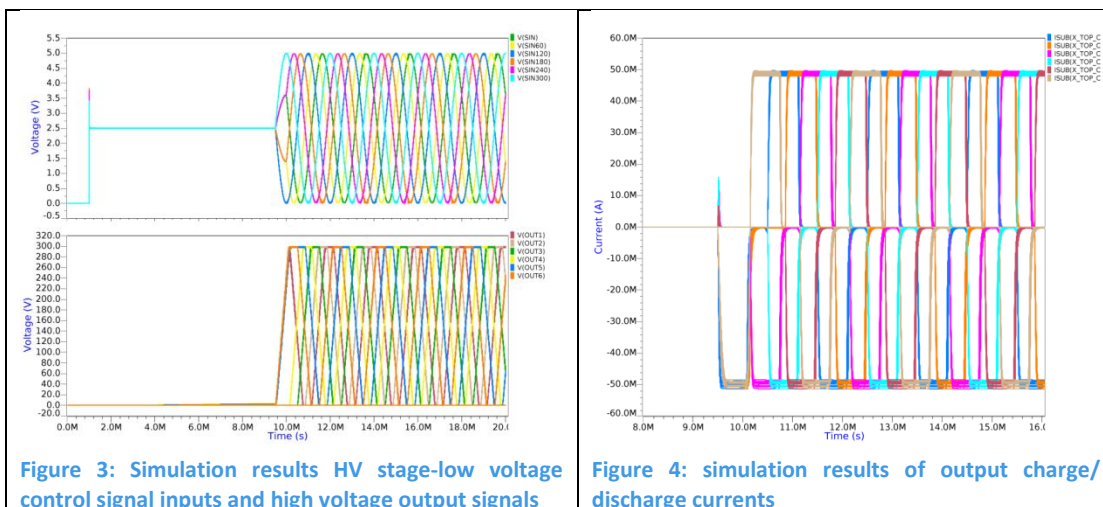


Figure 5 shows the block diagram of the HV ASIC system.

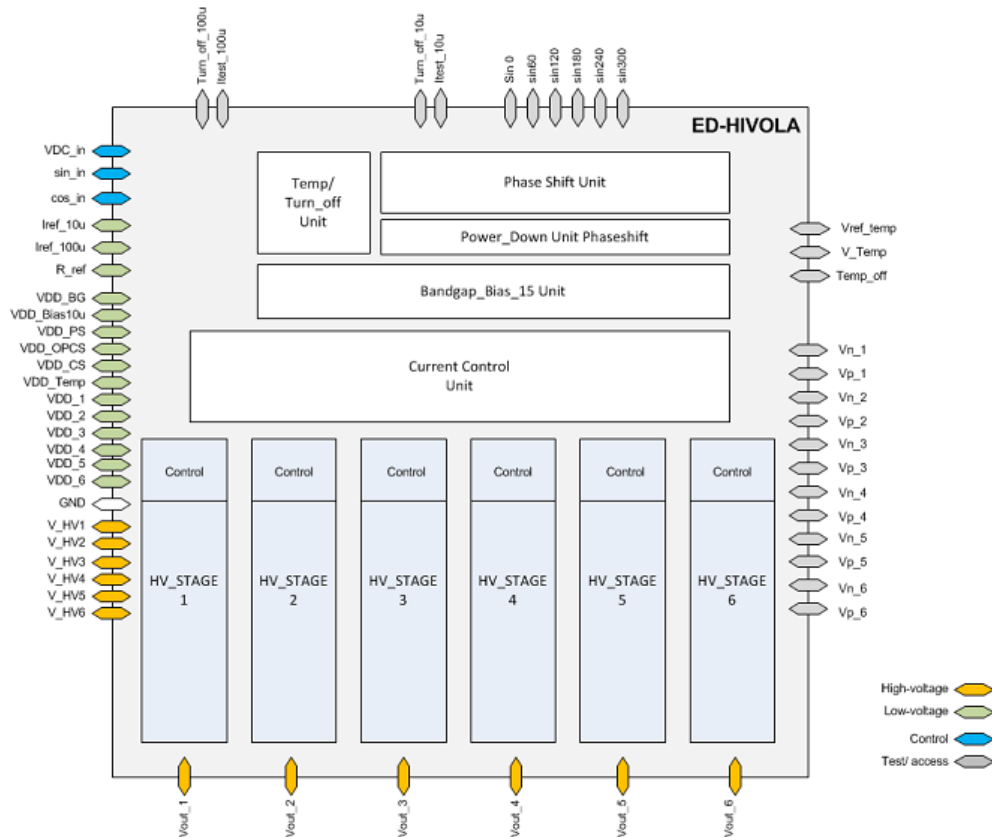


Figure 5: Block diagram- HV ASIC System

1.3 Results

The mock-up panel consists of three basic modules whereas the HV ASIC module and the actuator module are the main elements. The third module is designed to provide a useful common 230 V AC/ 24 V DC and 24 V DC/ HV DC conversion for easy use and demonstration by SFWA partners. In a final aircraft implementation it may be easy to be replaced by an optimized solution with respect to the board voltage supply capabilities.

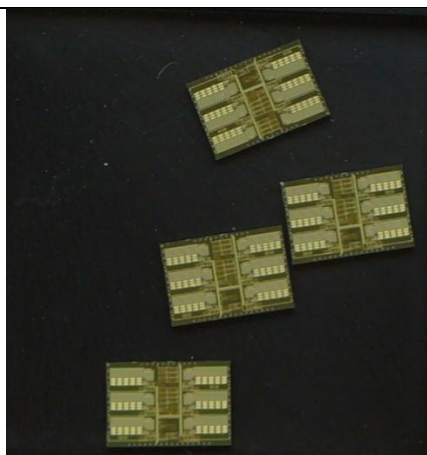


Figure 6: HV ASIC dies

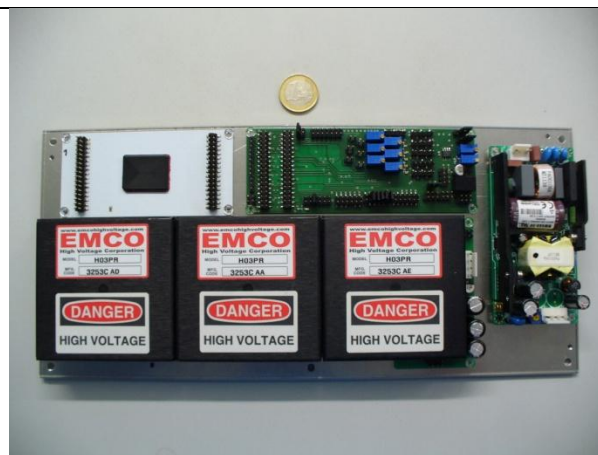


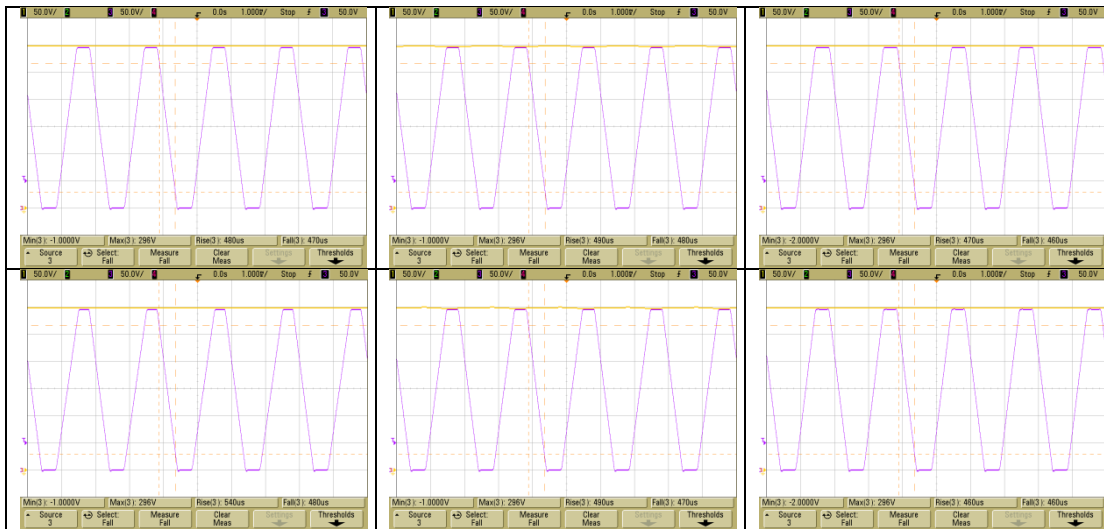
Figure 7: Mock-up Panel – electronic assembly

Table 1 shows exemplary the results of all six HV output stages with applied full load of 100nF with 300 V/ 500 Hz and Table 2 the related output signals.

Table 1: Summary of all HV stage output signals

HV_Amp	Min [V]	Max [V]	t _{rise} 90% [s]	t _{fall} 90% [s]	V_Temp [V]	delta T [°C]
Out_1	0	296	480	470	1,47	33,8
Out_2	0	296	490	480	1,46	35
Out_3	0	296	470	460	1,44	39,4
Out_4	0	296	540	480	1,49	29
Out_5	0	296	490	470	1,48	31
Out_6	0	296	460	460	1,48	32

Table 2: Output signals of HV stages 1-6



1.4 Summary

An integrated high voltage circuit has been developed in order to drive high capacitive loads up to 600 nF and enable operation voltages up to 300 V. Due to the reduction of space, weight and power consumption this solution enables active flow control by MEMS based piezoelectric actuators for aircraft applications.